



In re Application of:
Chen et al.

Serial No.: 08/856,116

Confirmation No.: 2582

Filed: May 14, 1997

For: **RELIABILITY BARRIER
INTEGRATION FOR CU
APPLICATION**

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

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Group Art Unit: 2814

Examiner: G. Peralta

CERTIFICATE OF MAILING  
37 CFR 1.8

I hereby certify that this correspondence is being deposited on  
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12/20/01                      Kimberly M. [Signature]  
Date                                      Signature

**RESPONSE TO FINAL OFFICE ACTION DATED OCTOBER 10, 2001**

In response to the Final Office Action dated October 10, 2001, having a shortened statutory period for response set to expire on January 10, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below.

### THE PENDING CLAIMS:

15. A method of filling a feature in a dielectric layer, comprising:
  - a) depositing a first barrier layer over a blanket dielectric layer;
  - b) forming a feature through the first barrier layer and the dielectric layer to expose an underlayer;
  - c) depositing a second barrier layer on a bottom and sidewalls in the feature;
  - d) removing the second barrier layer formed at the bottom of the feature;and